

## STGF20NB60S

## N-CHANNEL 13A - 600V TO-220FP PowerMESH™ IGBT

**Table 1: General Features** 

TYPE	V <sub>CES</sub>	V <sub>CE(sat)</sub> (Max) @25°C	<b>Ic</b> @100°C
STGF20NB60S	600 V	< 1.7 V	13 A

- LOW ON-VOLTAGE DROP (Vcesat)
- HIGHT CURRENT CAPABILITY
- OFF LOSSES INCLUDE TAIL CURRENT
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)

#### **DESCRIPTION**

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH IGBTs, with outstanding performances. The suffix "S" identifies a family optimized to achieve minimum on-voltage drop for low frequency to applications (<1kHz).

#### **APPLICATIONS**

- LIGHT DIMMER
- STATIC RELAYS
- MOTOR CONTROL

Figure 1: Package

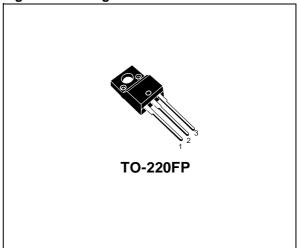
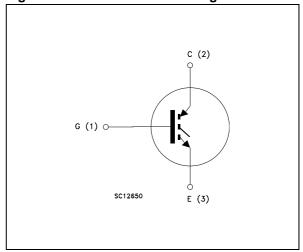


Figure 2: Internal Schematic Diagram



**Table 2: Order Code** 

PART NUMBER	MARKING	PACKAGE	PACKAGING	
STGF20NB60S	STGF20NB60S GF20NB60S		TUBE	

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**Table 3: Absolute Maximum ratings** 

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage (V <sub>GS</sub> = 0)	600	V
V <sub>ECR</sub>	Emitter-Collector Voltage	20	V
V <sub>GE</sub>	Gate-Emitter Voltage	±20	V
Ic	Collector Current (continuous) at T <sub>C</sub> = 25°C (#)		Α
Ic	Collector Current (continuous) at T <sub>C</sub> = 100°C (#)	13	Α
I <sub>CM</sub> (•)	Collector Current (pulsed)	70	Α
Ртот	Total Dissipation at T <sub>C</sub> = 25°C	40	
	Derating Factor	0.32	
V <sub>ISO</sub>	Insulation withstand voltage AC (t=1sec, Tc=25°C)	2500	V
T <sub>stg</sub>	Storage Temperature	55 to 150	
Tj	Operating Junction Temperature range		

<sup>(•)</sup> Pulse width limited by safe operating area

**Table 4: Thermal Data** 

		Min.	Тур.	Max.	
Rthj-case	Thermal Resistance Junction-case			3.15	°C/W
Rthj-amb	Thermal Resistance Junction-ambient			62.5	°C/W
TL	Maximum Lead Temperature for Soldering Purpose (1.6 mm from case, for 10 sec.)		300		°C

# **ELECTRICAL CHARACTERISTICS** (T<sub>CASE</sub> =25°C UNLESS OTHERWISE SPECIFIED) **Table 5: On/Off**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>BR(CES)</sub>	Collector-Emitter Breakdown Voltage	$I_C = 250 \mu A, V_{GE} = 0$	600			V
V <sub>BR(ECS)</sub>	Emitter-Collector Breakdown Voltage	n I <sub>C</sub> = 1mA, V <sub>GE</sub> = 0 20			V	
I <sub>CES</sub>	Collector cut-off Current (V <sub>GE</sub> = 0)	$V_{CE}$ = Max Rating, $T_{C}$ = 25 °C $V_{CE}$ = Max Rating, $T_{C}$ = 125 °C			10 100	μA μA
I <sub>GES</sub>	Gate-Emitter Leakage Current (V <sub>CE</sub> = 0)	$V_{GE} = \pm 20V$ , $V_{CE} = 0$			±100	nA
V <sub>GE(th)</sub>	Gate Threshold Voltage	$V_{CE} = V_{GE}, I_{C} = 250 \mu\text{A}$	2.5		5	V
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	V <sub>GE</sub> = 15V, I <sub>C</sub> = 20 A, Tj= 25°C V <sub>GE</sub> = 15V, I <sub>C</sub> = 20A, Tj=150°C		1.25 1.2	1.7	V V

<sup>(#)</sup> Calculated according to the iterative formula:

$$I_{C}(T_{C}) = \frac{T_{JMAX} - T_{C}}{R_{THJ-C} \times V_{CESAT(MAX)}(T_{C}, I_{C})}$$

#### **ELECTRICAL CHARACTERISTICS (CONTINUED)**

#### **Table 6: Dynamic**

Symbol	Parameter Test Conditions		Min.	Тур.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	V <sub>CE</sub> = 10 V , I <sub>C</sub> = 8 A		20		S
C <sub>ies</sub>	Input Capacitance $V_{CE} = 25 \text{ V, f} = 1 \text{ MHz, V}_{GE} = 0$			1820		pF
C <sub>oes</sub>	Output Capacitance			167		pF
C <sub>res</sub>	Reverse Transfer Capacitance			27		pF
Q <sub>g</sub> Q <sub>ge</sub> Q <sub>gc</sub>	Total Gate Charge Gate-Emitter Charge Gate-Collector Charge	$V_{CC} = 480 \text{ V}, I_{C} = 20 \text{ A},$ $V_{GE} = 15 \text{ V}$ (see Figure 19)		83 10 27	115	nC nC nC
I <sub>CL</sub>	Turn-off SOA minimum current	$V_{clamp} = 480 \text{ V}$ , $Tj = 125^{\circ}\text{C}$ $R_G = 100 \Omega$	80			Α

<sup>(1)</sup> Pulsed: Pulse duration= 300 µs, duty cycle 1.5%

#### Table 7: Switching On

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on Delay Time Current Rise Time Turn-on Current Slope	$V_{CC} = 480 \text{ V}, I_{C} = 20 \text{ A}$ $R_{G} = 100 \Omega, V_{GE} = 15 \text{ V}$ (see Figure 17)		92 70 340		ns ns A/µs
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on Delay Time Current Rise Time Turn-on Delay Time	$V_{CC} = 480 \text{ V, } I_{C} = 20 \text{ A}$ $R_{G} = 100 \Omega, V_{GE} = 15 \text{ V,}$ $T_{J} = 125^{\circ}\text{C} \text{ (see Figure 17)}$		80 73 320		ns ns A/µs

#### Table 8: Switching Off

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>c</sub>	Cross-over Time	$V_{CC} = 480 \text{ V}, I_{C} = 20 \text{ A},$		1.6		μs
$t_r(V_{off})$	Off Voltage Rise Time	$R_G = 100 \Omega$ , $V_{GE} = 15 V$ $T_{J} = 25 °C$		0.78		μs
t <sub>d</sub> (off)	Turn-off Delay Time	(see Figure 17)		1.1		μs
t <sub>f</sub>	Current Fall Time			0.79		μs
t <sub>c</sub>	Cross-over Time	$V_{CC} = 480 \text{ V}, I_{C} = 20 \text{ A},$		2.4		μs
$t_r(V_{off})$	Off Voltage Rise Time	$R_G = 100 \Omega$ , $V_{GE} = 15 V$ $T_I = 125 °C$		1.1		μs
t <sub>d</sub> (off)	Turn-off Delay Time	(see Figure 17)		2.4		μs
t <sub>f</sub>	Current Fall Time			1.2		μs

#### **Table 9: Switching Energy**

Symbol	Parameterr	Test Conditions	Min.	Тур.	Max	Unit
Eon (2) E <sub>off</sub> (3) E <sub>ts</sub>	Turn-on Switching Losses Turn-off Switching Loss Total Switching Loss	$V_{CC} = 480 \text{ V}, I_{C} = 20 \text{ A}$ $R_{G} = 100 \Omega, V_{GE} = 15 \text{V},$ (see Figure 18)		0.84 7.4 8.24		mJ mJ mJ
Eon (2) E <sub>off</sub> (3) E <sub>ts</sub>	Turn-on Switching Losses Turn-off Switching Loss Total Switching Loss	$V_{CC} = 480 \text{ V, } I_{C} = 20 \text{ A}$ $R_{G} = 100 \Omega$ , $V_{GE} = 15 \text{V,Tj} = 125 ^{\circ}\text{C}$ (see Figure 18)		0.86 11.5 12.4		mJ mJ mJ

<sup>(2)</sup> Eon is the turn-on losses when a typical diode is used in the test circuit in figure 2. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode.

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<sup>(3)</sup> Turn-off losses include also the tail of the collector current.

Figure 3: Output Characteristics

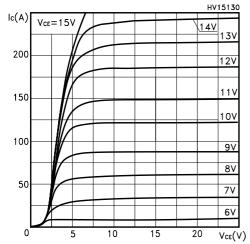


Figure 4: Transconductance

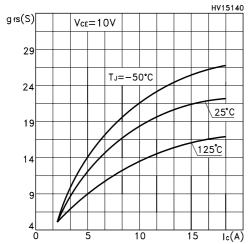
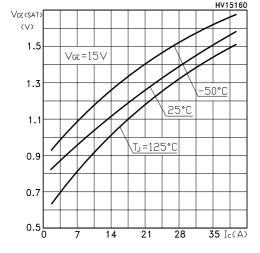


Figure 5: Collector-Emitter On Voltage vs Collector Current



**Figure 6: Transfer Characteristics** 

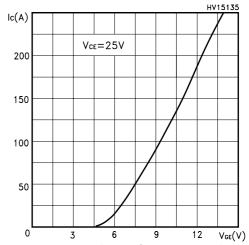


Figure 7: Normalized Collector-Emitter On Voltage vs Temperature

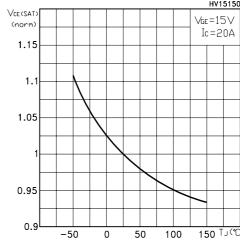


Figure 8: Gate Threshold vs Temperature

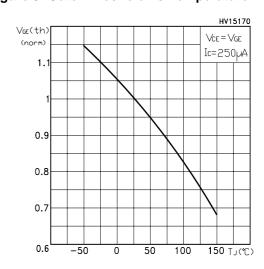


Figure 9: Normalized Breakdown Voltage vs Temperature

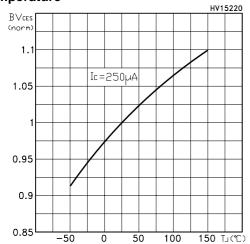


Figure 10: Capacitance Variations

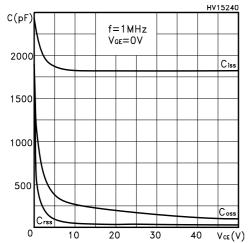


Figure 11: Switching Losses vs Temperature

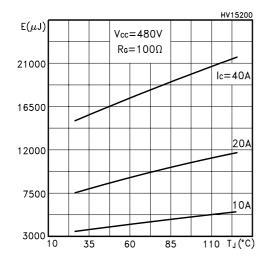


Figure 12: Gate Charge vs Gate-Emitter Voltage

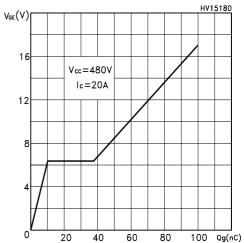


Figure 13: Switching Losses vs Gate Charge

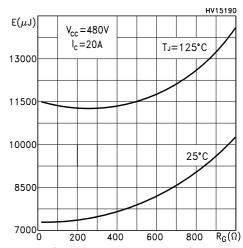
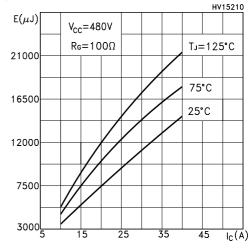


Figure 14: Switching Losses vs Collector Current



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Figure 15: Thermal Impedance

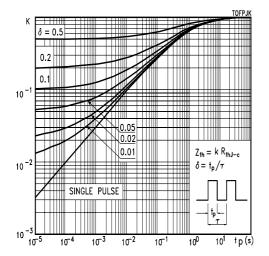


Figure 16: Collector-Emitter Diode Characteristics

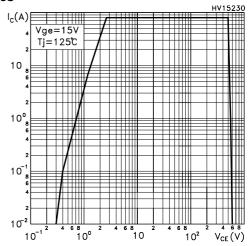


Figure 17: Test Circuit for Inductive Load Switching

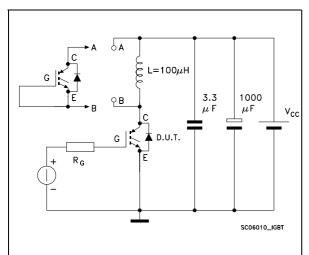


Figure 19: Gate Charge Test Circuit

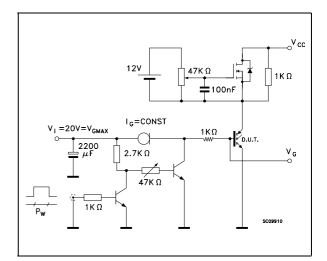
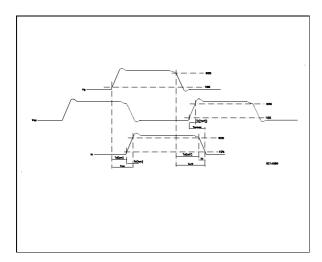


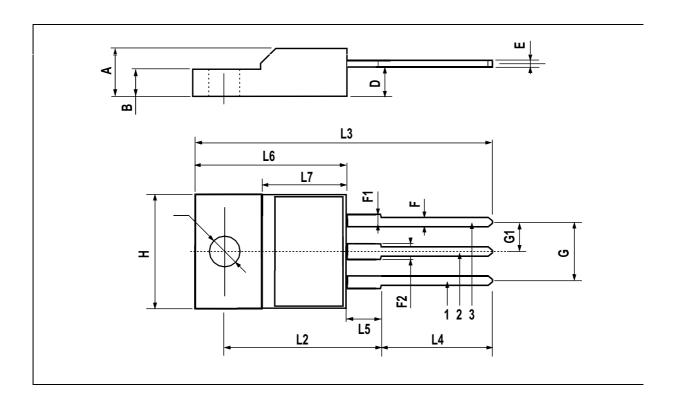
Figure 18: Switching Waveforms



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## **TO-220FP MECHANICAL DATA**

DIM		mm.			inch	
DIM.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030	0.03	
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



### **Table 10: Revision History**

Date	Revision	Description of Changes
17-Dec-2004	2	New template, no content change

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